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DRC2643T0L

Silicon NPN epitaxial planar type

For digital circuits / Muting

■ Features

- Low collector-emitter saturation voltage $V_{ce(sat)}$
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

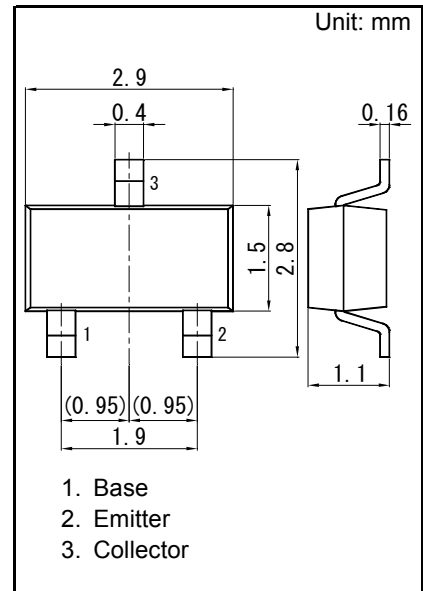
■ Marking Symbol: TU

■ Packaging

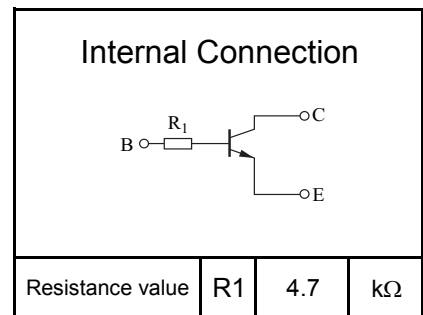
Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	VCBO	30	V
Collector-emitter voltage (Base open)	VCEO	20	V
Emitter-base voltage (Collector open)	VEBO	5	V
Collector current	IC	600	mA
Total power dissipation	PT	200	mW
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C



Panasonic	Mini3-G3-B
JEITA	SC-59A
Code	TO-236AA/SOT-23



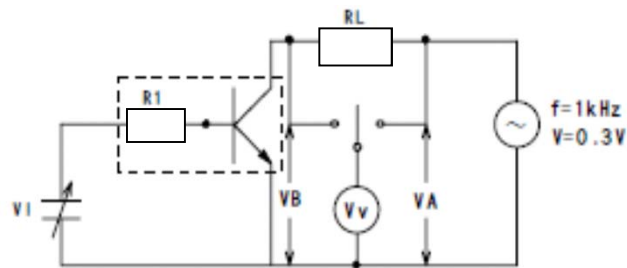
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = 10 μA, IE = 0	30			V
Collector-emitter voltage (Base open)	VCEO	IC = 1 mA, IB = 0	20			V
Emitter-base voltage (Collector open)	VEBO	IE = 10 μA, IC = 0	5			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = 30 V, IE = 0			1	μA
Emitter-base cutoff current (Collector open)	IEBO	VEB = 5 V, IC = 0			1	μA
Forward current transfer ratio *1	hFE	VCE = 5 V, IC = 50 mA	100		600	-
Collector-emitter saturation voltage	VCE(sat)	IC = 50 mA, IB = 2.5 mA			80	mV
Input resistance	R1		-30%	4.7	+30%	kΩ
On resistance *2	Ron	VI = 7 V, RL = 1 kΩ, f = 1 kHz		1.4		Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. *1 Pulse Test

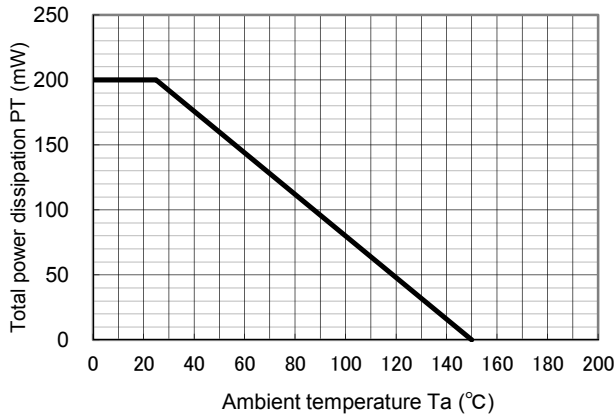
*2 On resistance test circuit



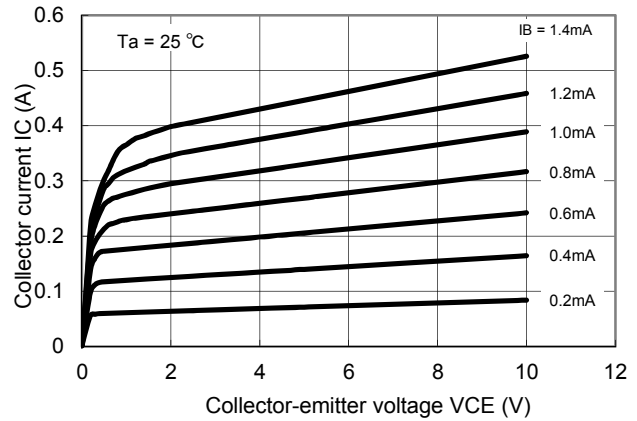
$$R_{on} = \frac{V_B}{V_A - V_B} \times R_L \quad (\Omega)$$

Technical Data (reference)

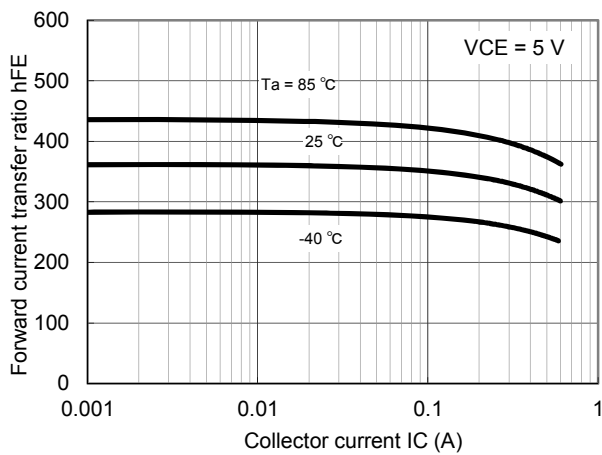
PT - Ta



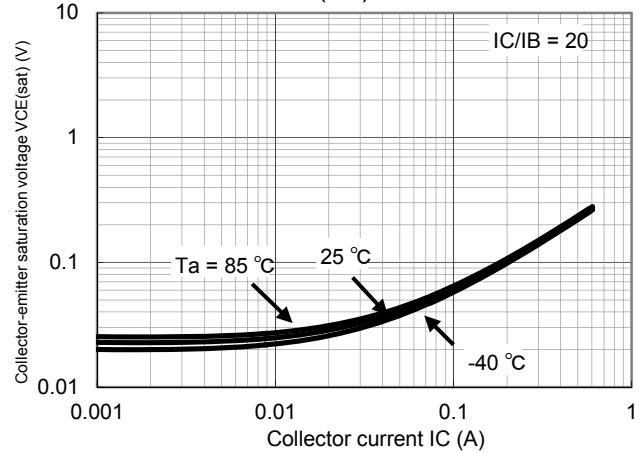
IC - VCE



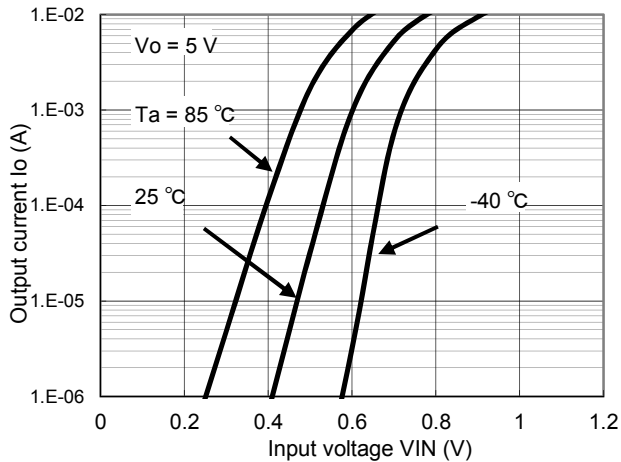
hFE - IC



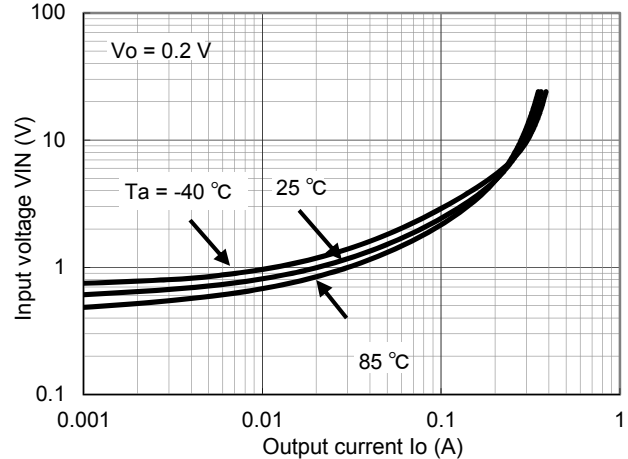
VCE(sat) - IC



Io - VIN



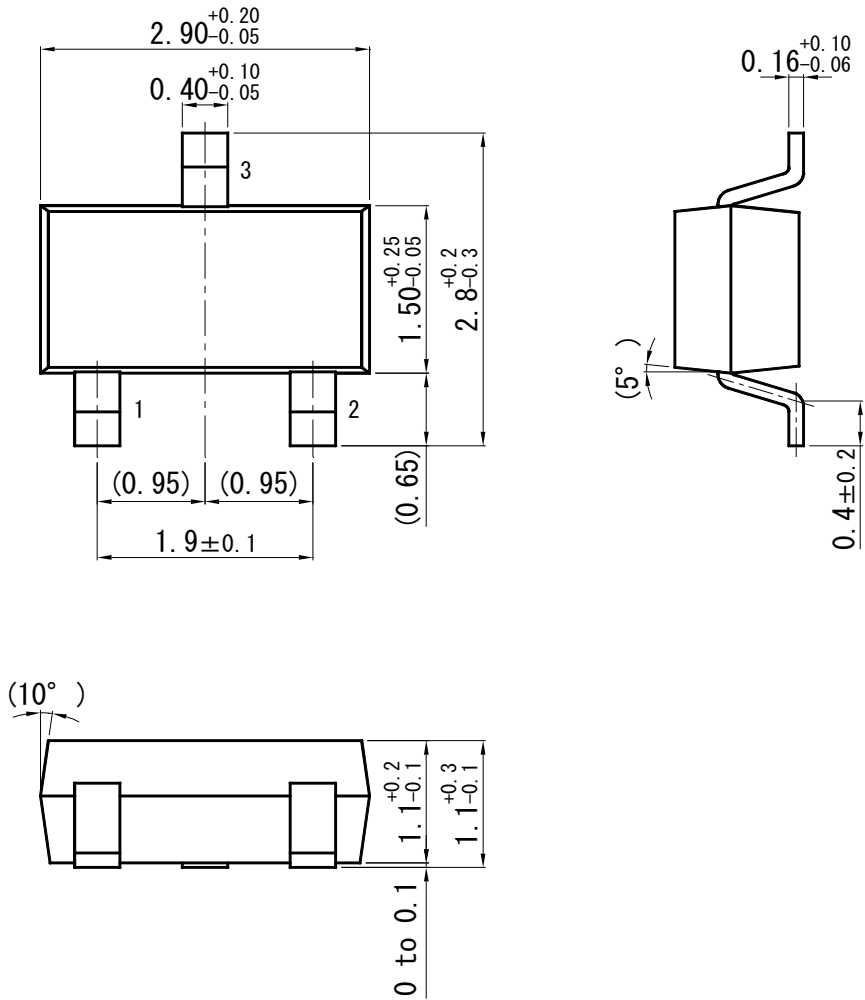
VIN - Io



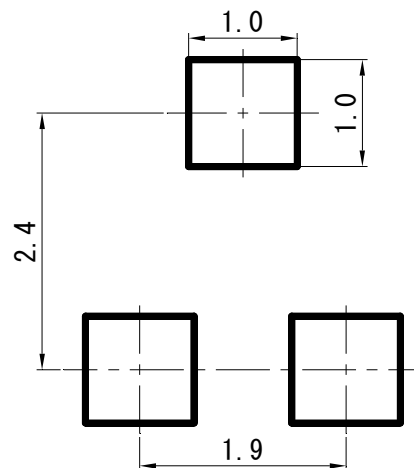


Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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